



Material Content Data Sheet



Sales Product Name		BTS432E2 E3062A		Issued		24. January 2018		
MA#		MA001813264						
Package		PG-TO263-5-2		Weight*		1501.36 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.065	0.87	0.87	8702	8702
leadframe	inorganic material	phosphorus	7723-14-0	0.237	0.02		158	
	non noble metal	iron	7439-89-6	0.790	0.05		526	
	non noble metal	copper	7440-50-8	788.527	52.52	52.59	525210	525894
	non noble metal	aluminium	7429-90-5	1.577	0.10	0.10	1050	1050
wire	non noble metal	aluminium	7429-90-5	1.577	0.10	0.10	1050	1050
encapsulation	organic material	carbon black	1333-86-4	6.246	0.42		4160	
	inorganic material	antimonytrioxide	1309-64-4	13.060	0.87		8699	
	plastics	brominated resin	-	14.763	0.98		9833	
	plastics	epoxy resin	-	107.884	7.19		71858	
	inorganic material	silicondioxide	60676-86-0	425.858	28.36	37.82	283650	378200
leadfinish	non noble metal	tin	7440-31-5	10.339	0.69	0.69	6887	6887
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		5	
	non noble metal	nickel	7440-02-0	3.422	0.23	0.23	2279	2284
glue	plastics	Polyimide	26023-21-2	0.410	0.03	0.03	273	273
solder	non noble metal	tin	7440-31-5	0.142	0.01		94	
	noble metal	silver	7440-22-4	0.177	0.01		118	
	non noble metal	lead	7439-92-1	6.767	0.45	0.47	4507	4719
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		22	
	non noble metal	iron	7439-89-6	0.108	0.01		72	
	non noble metal	copper	7440-50-8	107.943	7.19	7.20	71897	71991
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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